

ABSTRACT

LASER PROCESSING APPARATUS

Disclosed herein is a laser processing apparatus for forming a separation layer inside an ingot by applying a laser beam to an end surface of the ingot in the condition where the focal point of the laser beam is set inside the ingot, the laser beam having a transmission wavelength to the ingot. The laser processing apparatus includes a holding unit for holding the ingot, a moving unit for moving the holding unit in a direction parallel to the end surface of the ingot held by the holding unit, a laser beam applying unit for applying the laser beam to the ingot held by the holding unit, an imaging unit for detecting the position of the ingot in the direction parallel to the end surface of the ingot, and a height detecting unit for detecting the height of the end surface of the ingot held by the holding unit.

(Figure 2A)